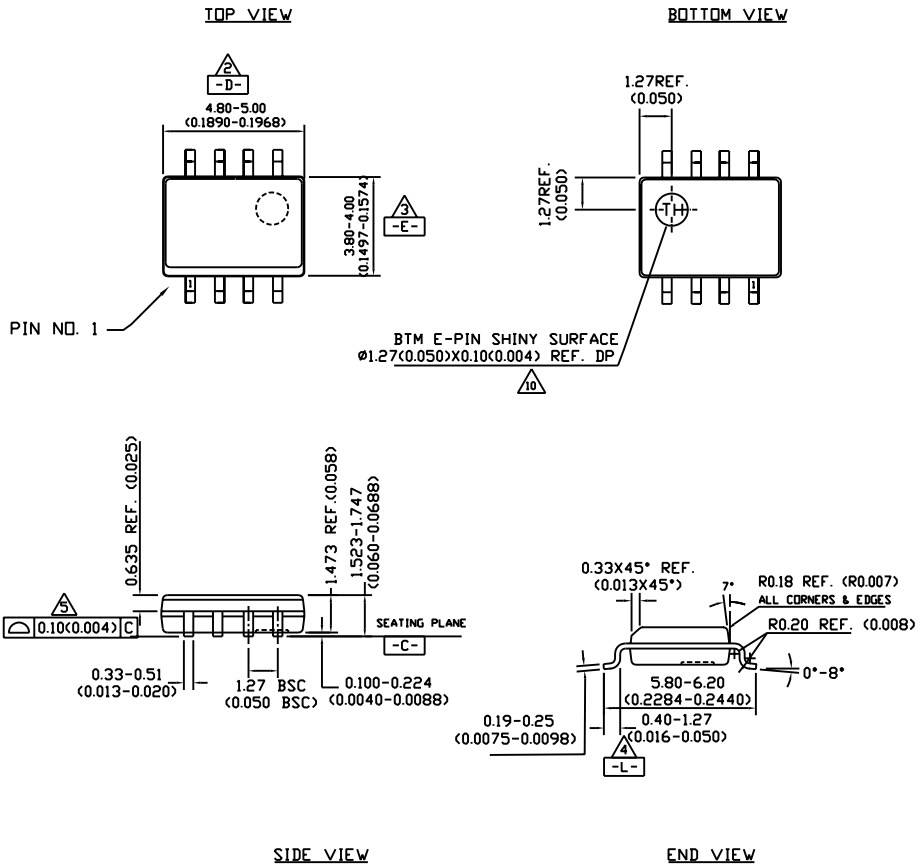



| REV | DESCRIPTION    | DATE     |
|-----|----------------|----------|
| A   | ORIGINAL ISSUE | JUL 5'00 |
|     |                |          |
|     |                |          |



- NOTES:
- 1.DIMENSIONING & TOLERANCING PER ANSI.Y14.5M-1982.
  - 2.DIMENSION "D" DOES NOT INCLUDE MOLD FLASH,PROTRUSIONS OR GATE BURRS.MOLD FLASH,PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15MM(0.006") PER SIDE.
  - 3.DIMENSION "E" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION,INTER-LEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25MM(0.010") PER SIDE.
  - 4."L" IS A LENGTH OF TERMINAL FOR SOLDERING TO SUBSTATE.
  - 5.FORMED LEAD SHALL BE PLANED WITH RESPECT TO ONE ANOTHER WITHIN 0.10MM(0.004") AT SEATING PLANE"C"
  - 6.BODY FINISH : 18-24 CHARMILLES.
  - 7.CONTROLLING DIMENSION : MILLIMETER CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT.
  - 8.LEAD FINISH IS ELECTROPLATING WITH A THICKNESS OF 300 - 800 MICRINCH.
  - 9.CHARACTER HEIGHT ON EJECTOR PIN IS 0.635MM(0.025").
  - "TH" STAND FOR THAILAND.
  - 10.RAISED CHARACTER NOT TO PROTRUDE BEYOND SURFACE OR PACKAGE BODY.

|   |                              |  |                         |                      |
|---|------------------------------|--|-------------------------|----------------------|
|  | DRAWN BY:<br>ANUPHAB U.      | TITLE:<br><b>8 LD SOIC (JEDEC) PACKAGE OUTLINE DWG.<br/>150 MIL BODY WIDTH FAMILY (MGP MOLD)</b> |                         |                      |
|   | CHECKED BY:<br>NATAPORN C.   | DATE : JUL 5'00  | REF. NO. : JEDEC-MS-012 | SCALE : NOT TO SCALE |
|   | APPROVED BY:<br>THANAPONG I. | DWG. NO. <b>J008PO-01</b>  | REV. A                  | SHEET 1 OF 1         |
|   | APPROVED BY:<br>VIRAT T.     |  |                         |                      |